

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of: FUJISAWA, et al.

Serial No.: 09/766,656

Filed: January 23, 2001

Group Art Unit: 2814

Prior Examiner: D. Graybill

P.T.O. Confirmation No.: 1144

FOR: METHOD AND MOLD FOR MANUFACTURING SEMICONDUCTOR DEVICE, SEMICONDUCTOR DEVICE, AND METHOD FOR MOUNTING THE DEVICE

AMENDMENT TRANSMITTAL

Commissioner for Patents  
Washington, D.C. 20231

November 26, 2002

Sir:

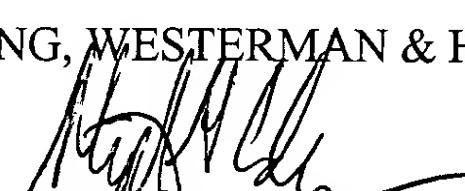
Transmitted herewith is an Amendment in the above-identified application.  
The fee has been calculated as shown below:

		CLAIMS AS AMENDED					
	Claims Remaining After Amendment	Highest Number Previously Paid For		Present Extra	Small Entity	Large Entity	Additional Fee
Total Claims	23	20	=	3	X \$9	X \$18	54.00
Independent Claims	6	8	=	0	X \$42	X \$84	0
First Presentation of Multiple Dependent Claims					\$140	280	
TOTAL FEES ENCLOSED:							\$54.00

- Enclosed please find our check in the amount of \$54.00 for the additional claims fee in connection with this amendment.
- The Commissioner is hereby authorized to charge payment for any additional fees associated with this communication or credit any overpayment to Deposit Account No. 01-2340. Two duplicates of this sheet are attached.

Respectfully submitted,

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**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re the Application of: FUKASAWA, et al.

Group Art Unit: 2814 929/03

Serial No.: 09/766,656

Prior Examiner: D. Graybill

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**For. METHOD AND MOLD FOR MANUFACTURING SEMICONDUCTOR DEVICE,  
SEMICONDUCTOR DEVICE, AND METHOD FOR MOUNTING THE DEVICE**

## **SECOND SUPPLEMENTAL PRELIMINARY AMENDMENT**

Commissioner for Patents  
Washington, D.C. 20231

Date: November 26, 2002

Sir:

Further to the Supplemental Preliminary Amendment filed February 21, 2002, please amend the above-captioned patent application as follows:

## IN THE CLAIMS:

**Please add new claims 111-120 as follows:**

111. A method for fabricating a semiconductor device comprising:

a resin sealing step of loading a wiring board having a flexible member on which a semiconductor element and leads are arranged onto a mold and supplying sealing resin to the semiconductor element so as to seal the semiconductor element; and

a protruding electrode forming step of forming protruding electrodes so as to be

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